



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
MALONEY, et al.

Application No. 10/027,935

Filed: December 21, 2001

For: **Apparatus and Method for
Chemical-Mechanical Polishing
(CMP) Head Having Direct
Pneumatic Wafer Polishing
Pressure**

Examiner: ELY, TIMOTHY V
Art Unit: 3724

Confirmation No.: 2631

Palo Alto, California

Certificate of Mailing

I hereby certify that this correspondence is being deposited in the United States Mail, postage prepaid in an envelope addressed to Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on July 20, 2004.

By: Leslie Hoffmann
Leslie Hoffmann

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This Amendment is made in response to the Office Action mailed April 20, 2004 imposing a 1-month response period restriction/election requirement on the claims and is accompanied by a Petition for 2-Month Extension of Time to extend the due date from 20 May 2004 to 20 July 2004.
Applicant elects Group I (Claims 1, 9-16 and 23-25) without traverse and added Claims 26-31 which
Applicant submits belong to Group I.

A listing of the Claims begins on page 2 of this paper.

Remarks/Arguments begin on page 12 of this paper.

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03 FC:1202 72.00 OP